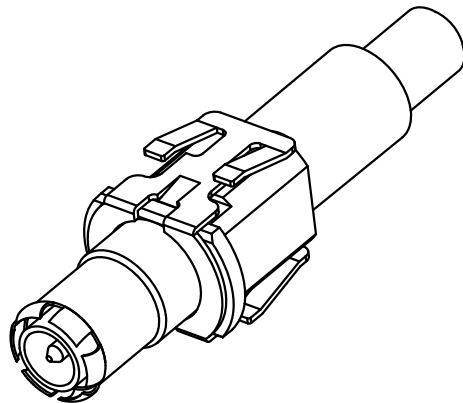
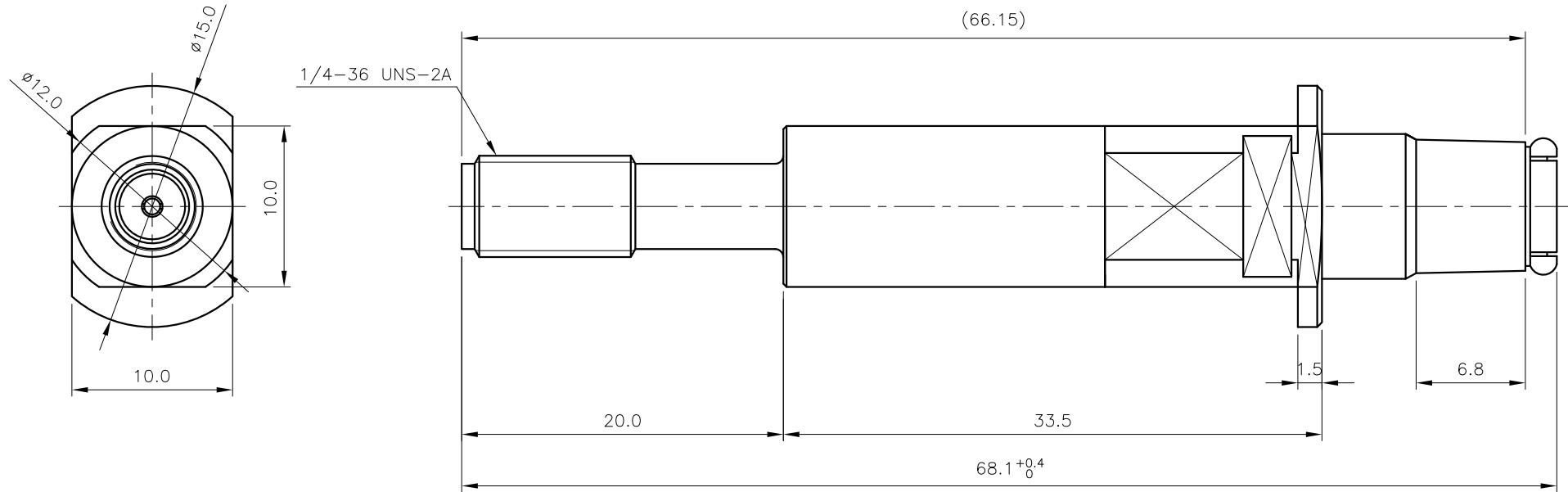


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	Y.H.CHOI	2010.11.02.
1	[설번No.201603-0011] LOCK PANNEL 현품에 맞게 변경으로 인한 CODE 변경	H.J.LEE	I.C.KIM	2016.03.25.



* PCB 두께 권장 사양 : 3.2t ±0.1mm

1	8	JACK PANEL	1	SUS	부동태 처리	DSR00070-N/2 DSR00070-N/1
	7	JACK	1	BeCu	Nickel Plate	DJA00039-5/1
	6	INSULATOR	1	TEFLON		DIN01848-N/1
	5	INSULATOR	1	TEFLON		DAI00126-N/1
	4	CONTACT	1	MBsBD	Gold Plate	DCT02366-5/1
	3	CONTACT	1	BeCu	Gold Plate	DCT02365-5/1
	2	BODY	1	MBsBD	Nickel Plate	DBD02847-5/1
	1	BODY	1	MBsBD	Nickel Plate	DBD02846-5/1
NO.		DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2016. 03. 25.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY I.C.KIM				
MATERIAL _____		CHECKED BY	TITLE SMA50 (J) TRU50 (P) PANEL LOCK			
		DRAWN BY H.J.LEE				
FINISH _____		SCALE 2.5/1	UNIT mm		A4	DWG NO. AD00448-7/1
						REVISION 1